

| L Number | Hits  | Search Text                                 | DB  | Time stamp       |
|----------|-------|---|---|------------------|
| -        | 2     | ("5489966").PN.                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:09 |
| -        | 56197 | semiconductor.as.                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:10 |
| -        | 73    | semiconductor-leading-edge-technologies.as. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:17 |
| -        | 2     | jp-2001006107-\$.did.                       | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:23 |
| -        | 0     | jp-20013075598-\$.did.                      | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:19 |
| -        | 0     | jp-13006107-\$.did.                         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:21 |
| -        | 0     | jp-133075598-\$.did.                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:21 |
| -        | 4     | kim-jeong-yeal.in.                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/01 14:24 |
| -        | 409   | (250/201.2).CCLS.                           | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/22 12:50 |
| -        | 677   | (250/204).CCLS.                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 12:29 |
| -        | 934   | (250/548).CCLS.                             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 12:30 |
| -        | 562   | (250/559.45).CCLS.                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 12:30 |

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| - | 1981 | (355/53).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/22 12:50 |
| - | 1204 | (355/55).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:53 |
| - | 959  | (355/68).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:53 |
| - | 578  | wafer and 250/201.2,204,548,559.45.ccls.                            | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:02 |
| - | 13   | wafer and 250/204.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:55 |
| - | 481  | wafer and 250/548.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:55 |
| - | 56   | wafer and 250/559.45.ccls.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:55 |
| - | 37   | wafer and 250/201.2.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 13:55 |
| - | 111  | wafer with edge and<br>250/201.2,204,548,559.45.ccls.               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:14 |
| - | 165  | wafer with edge and 355/53,55,68.ccls.                              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:12 |
| - | 17   | wafer with edge with exposure and<br>250/201.2,204,548,559.45.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/10 14:36 |
| - | 64   | wafer with edge with exposure and<br>355/53,55,68.ccls.             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:21 |

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| - | 6    | wafer with edge with exposure with light and 250/201.2,204,548,559.45.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:21 |
| - | 37   | wafer with edge with exposure with light and 355/53,55,68.ccls.             | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/04/03 14:32 |
| - | 2    | jp-09260263-\$.did.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/22 11:23 |
| - | 295  | yamada-kohei.in.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/22 11:09 |
| - | 2    | jp-61128522-\$.did.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/09/22 11:27 |
| - | 2591 | (250/201.2,204,548,559.45).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 10:30 |
| - | 4031 | (355/53,55,68).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 10:31 |
| - | 3165 | (355/53,55).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 10:32 |
| - | 2226 | (355/53).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 10:32 |
| - | 119  | wafer with height and 250/201.2,204,548,559.45.ccls.                        | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/10 14:37 |
| - | 3    | wafer with edge with height and 250/201.2,204,548,559.45.ccls.              | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/10 14:38 |
| - | 203  | height and wafer and 250/201.2,204,548,559.45.ccls.                         | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/10 14:38 |

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| - | 33    | (height adj wafer) and<br>250/201.2,204,548,559.45.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/11 16:08 |
| - | 10    | 4870288.URPN.  | USPAT   | 2004/03/10 14:53 |
| - | 33    | (height adj wafer) and<br>250/201.2,204,548,559.45.ccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/11 16:09 |
| - | 23    | optical and sensor and focus and light and ((height<br>adj wafer) and 250/201.2,204,548,559.45.ccls.)                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/11 16:29 |
| - | 23    | height and (optical and sensor and focus and light<br>and ((height adj wafer) and<br>250/201.2,204,548,559.45.ccls.))          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/11 16:29 |
| - | 8     | height and edge and (optical and sensor and focus<br>and light and ((height adj wafer) and<br>250/201.2,204,548,559.45.ccls.)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/11 16:29 |
| - | 823   | (250/559.22,559.27,201.4).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:15 |
| - | 13216 | wafer and (thickness or profile or depth) and focus  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 07:38 |
| - | 70    | wafer and (thickness or profile or depth) and focus<br>and ((250/559.22,559.27,201.4).CCLS.)                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 07:54 |
| - | 70    | wafer and (thickness or profile or depth) and focus<br>and ((250/559.22,559.27,201.4).CCLS.)                                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 08:03 |
| - | 34    | wafer and edge and (thickness or profile or depth)<br>and focus and ((250/559.22,559.27,201.4).CCLS.)                          | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 08:03 |
| - | 4275  | (355/53,55,68).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/03/22 10:31 |
| - | 2657  | (250/201.2,204,548,559.45).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:14 |

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| - | 2451 | (355/53).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:15 |
| - | 1313 | (355/55).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:15 |
| - | 981  | (355/68).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:15 |
| - | 2709 | (250/201.2,204,548,559.45).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:17 |
| - | 838  | (250/559.22,559.27,201.4).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:22 |
| - | 2690 | (355/53).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:25 |
| - | 1368 | (355/55).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:28 |
| - | 992  | (355/68).CCLS.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:31 |
| - | 1    | wafer and edge and (exposure adj light) and optical and sensor and focus and ((250/559.22,559.27,201.4).CCLS.) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:32 |
| - | 157  | wafer and edge and (exposure adj light) and optical and sensor and focus and ((355/53).CCLS.)                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:32 |
| - | 55   | wafer and edge and (exposure adj light) and optical and sensor and focus and ((355/55).CCLS.)                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:32 |
| - | 13   | wafer and edge and (exposure adj light) and optical and sensor and focus and ((355/68).CCLS.)                  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:32 |

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| - | 39 | wafer and edge and (exposure adj light) and optical and sensor and focus and ((250/201.2,204,548,559.45).CCLS.)                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:33 |
| - | 1  | (wafer with height) and edge and (exposure adj light) and optical and sensor and focus and ((250/559.22,559.27,201.4).CCLS.)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:33 |
| - | 64 | (wafer with height) and edge and (exposure adj light) and optical and sensor and focus and ((355/53).CCLS.)                    | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:34 |
| - | 25 | (wafer with height) and edge and (exposure adj light) and optical and sensor and focus and ((355/55).CCLS.)                    | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:34 |
| - | 8  | (wafer with height) and edge and (exposure adj light) and optical and sensor and focus and ((355/68).CCLS.)                    | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:34 |
| - | 20 | (wafer with height) and edge and (exposure adj light) and optical and sensor and focus and ((250/201.2,204,548,559.45).CCLS.)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:37 |
| - | 1  | (wafer with height with edge) and (exposure adj light) and optical and sensor and focus and ((250/201.2,204,548,559.45).CCLS.) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:37 |
| - | 0  | (wafer with height with edge) and (exposure adj light) and optical and sensor and focus and ((250/559.22,559.27,201.4).CCLS.)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:37 |
| - | 0  | (wafer with height with edge) and (exposure adj light) and optical and sensor and focus and ((355/68).CCLS.)                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:37 |
| - | 3  | (wafer with height with edge) and (exposure adj light) and optical and sensor and focus and ((355/53).CCLS.)                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:37 |
| - | 1  | (wafer with height with edge) and (exposure adj light) and optical and sensor and focus and ((355/55).CCLS.)                   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2004/08/20 08:44 |